Thyristors logic level

BT258S series

BT258M series

GENERAL DESCRIPTION

Glass passivated, sensitive gate thyristors in a plastic envelope, suitable for surface mounting, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

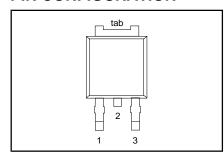
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V _{DRM} , V _{RRM} I _{T(AV)} I _{T(RMS)} I _{TSM}	BT258S (or BT258M)- Repetitive peak off-state voltages Average on-state current RMS on-state current Non-repetitive peak on-state current	500R 500 5 8 75	600R 600 5 8 75	800R 800 5 8 75	V A A A

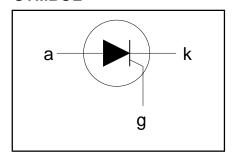
PINNING - SOT428

PIN NUMBER	Standard S	Alternative M
1	cathode	gate
2	anode	anode
3	gate	cathode
tab	anode	anode

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT	
V _{DRM} , V _{RRM}	Repetitive peak off-state voltages		-	-500R 500 ¹	-600R 600 ¹	-800R 800	>
I _{T(AV)} I _{T(RMS)} I _{TSM}	Average on-state current RMS on-state current Non-repetitive peak on-state current	half sine wave; $T_{mb} \le 111 ^{\circ}\text{C}$ all conduction angles half sine wave; $T_j = 25 ^{\circ}\text{C}$ prior to surge	-		5 8		A A
	0.1.0.0.0	t = 10 ms t = 8.3 ms	-		75 82		A A
l²t dl _⊤ /dt	I ² t for fusing Repetitive rate of rise of on-state current after triggering	t = 10 ms $I_{TM} = 10 \text{ A}; I_{G} = 50 \text{ mA};$ $dI_{G}/dt = 50 \text{ mA/}\mu\text{s}$	-		28 50		Α A²s A/μs
I _{GM} V _{GM} V _{RGM} P _{GM}	Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power		- - -		2 5 5 5		A V V W
P _{G(AV)} T _{stg} T _j	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- -40 -		0.5 150 125 ²		3°°°

September 1997 1 Rev 1.100

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

² Note: Operation above 110°C may require the use of a gate to cathode resistor of $1k\Omega$ or less.

BT258S series BT258M series

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Thermal resistance		-	-	2.0	K/W
R _{th i-a}	junction to mounting base Thermal resistance junction to ambient	pcb (FR4) mounted; footprint as in Fig.14	-	75	-	K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$	-	50	200	μΑ
l I	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	0.4	10	mΑ
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	0.3	6	mΑ
Ϊ́Τ	On-state voltage	$I_{T} = 16 \text{ A}$	-	1.3	1.5	V
V _{GT}	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.4	1.5	V
		$V_{\rm D} = V_{\rm DRM(max)}$; $I_{\rm T} = 0.1 \text{ A}$; $T_{\rm i} = 110 ^{\circ}\text{C}$	0.1	0.2	-	V
I_D, I_R	Off-state leakage current	$V_D = V_{DRM(max)}$; $V_R = V_{RRM(max)}$; $T_j = 125$ °C	-	0.1	0.5	mA

DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	V_{DM} = 67% $V_{DRM(max)}$; T_j = 125 °C; exponential waveform; R_{GK} = 100 Ω	50	100	-	V/μs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 10 \text{ A}; V_D = V_{DRM(max)}; I_G = 5 \text{ mA};$ $dI_G/dt = 0.2 \text{ A/}\mu\text{s}$	-	2	-	μs
t _q	Circuit commutated turn-off time	$V_D = 67\% \ V_{DRM(max)}; \ T_j = 125 \ ^{\circ}C; \ I_{TM} = 12 \ A; \ V_R = 24 \ V; \ dI_{TM}/dt = 10 \ A/\mu s; \ dV_D/dt = 2 \ V/\mu s; \ R_{GK} = 1 \ k\Omega$	-	100	-	μs

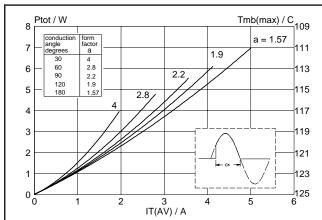


Fig.1. Maximum on-state dissipation, P_{tot} , versus average on-state current, $I_{T(AV)}$, where $a = form \ factor = I_{T(RMS)}/I_{T(AV)}$.

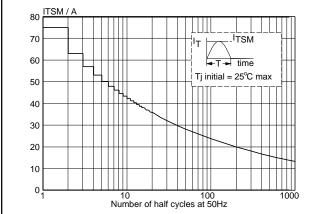


Fig.4. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

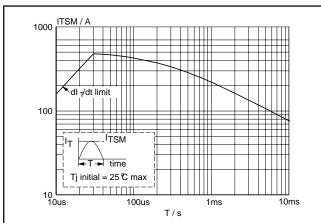


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 10$ ms.

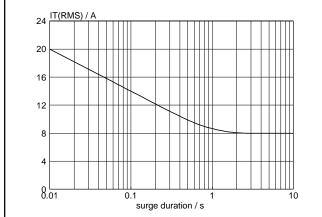


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 111$ °C.

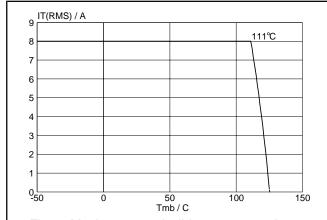
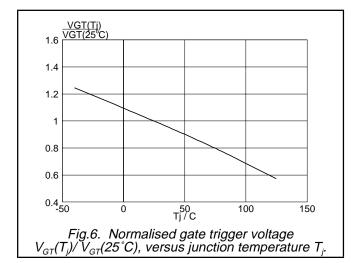
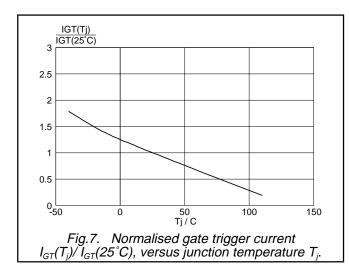


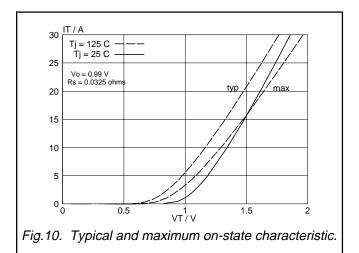
Fig.3. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

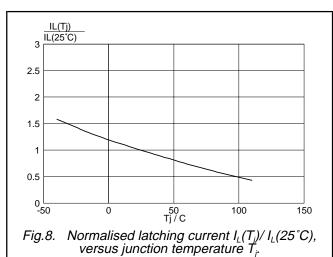


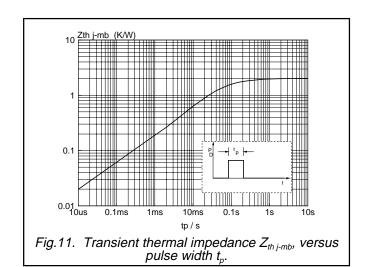
Thyristors logic level

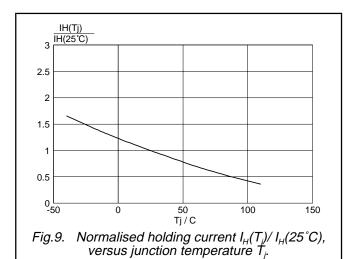
BT258S series BT258M series











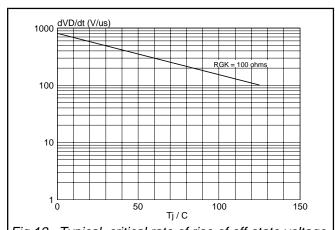


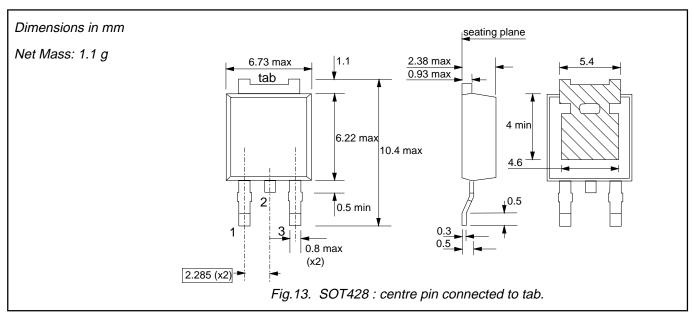
Fig.12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature T_i.

September 1997 4 Rev 1.100

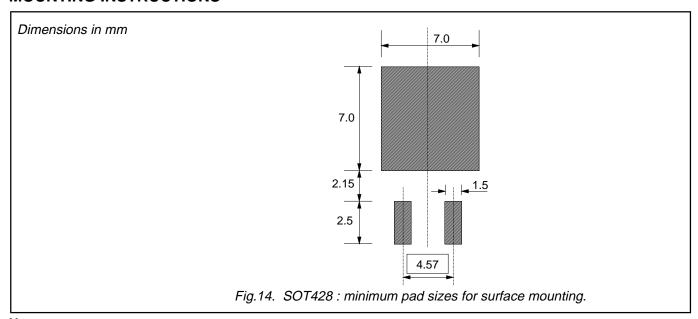
Thyristors logic level

BT258S series BT258M series

MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Plastic meets UL94 V0 at 1/8".

Thyri:	stors
logic	level

BT258S series BT258M series

DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification This data sheet contains final product specifications.					

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

© Philips Electronics N.V. 1997

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.